

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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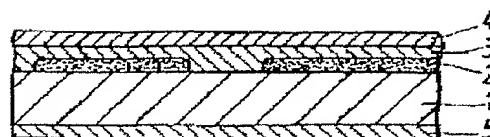
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APPLICANT : CMK CORP;

INVENTOR : KOINUMA YUICHI;

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TITLE : PRINTED WIRING BOARD HAVING  
MAGNETIC  
FIELD-ELECTROMAGNETIC WAVE  
SHIELD LAYER AND MANUFACTURE  
THEREOF



ABSTRACT : PURPOSE: To prevent noise such as a cross talk by intercepting a magnetic field and an electromagnetic wave generated from a circuit of a printed wiring board by one shield layer.

CONSTITUTION: On the surface and the rear of a printed wiring board, a magnetic field-electromagnetic wave shield layer 4 is provided on the surface whereon a wiring circuit 2 is formed, with an insulating layer 3 interlaid, and a magnetic field-electromagnetic wave shield layer 5 is provided directly on the rear whereon the wiring circuit is not formed. These magnetic field-electromagnetic wave shield layers are made to contain granular bodies prepared by coating high-permeability magnetic body powder having an initial permeability  $\mu$  of  $10^{-2}$  or above and a coercive force  $H_c$ [Oe] of 1 or below with copper or silver of high conductivity. On the occasion when the printed wiring board is manufactured, paste made to contain the granular bodies is prepared and this paste is applied on necessary parts of the printed wiring board and set, so that the magnetic field-electromagnetic wave shield layers be formed. A magnetic field and an electromagnetic wave are intercepted only by these layers.

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